

LASER ALIGNMENT TARGET

ABSTRACT OF THE DISCLOSURE

5 A technique to form a structure with a rough
topology (415) in a planarized semiconductor process. The
rough topology (415) is formed by creating cored contacts
(433). Subsequent process layers may be further stacked on
top of the cored contacts in order to augment the nonplanar
characteristics of the cored contacts. This rough topology
10 structure may be used to align integrated circuits and wafers.
An integrated circuit may be laser aligned using this
alignment structure.